

P-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^d	Q _g (Typ.)			
- 30	0.018 at V _{GS} = - 10 V	- 9.0	13 nC			
- 30	0.024 at $V_{GS} = -4.5 \text{ V}$	- 7.8	13110			

FEATURES

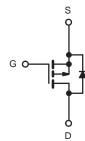
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R_g Tested

Pb-free BoHS

ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

- Load Switch
- · Battery Switch



P-Channel MOSFET

	SO-8	
S 1 S 2 S 3 G 4		8 D 7 D 6 D 5 D
	Top View	

ABSOLUTE MAXIMUM RATINGS T	A = 25 °C, unless other	erwise noted			
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	- 30	V		
Gate-Source Voltage	V_{GS}	± 20	V		
	T _C = 25 °C		- 9.0		
Continuous Proin Current (T. – 150 °C)	T _C = 70 °C		- 7.2		
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	l _D	- 7.0 ^{a, b}		
	T _A = 70 °C		- 5.6 ^{a, b}	Α	
Pulsed Drain Current	I _{DM}	- 30			
Continuous Course Dunin Die de Course	T _C = 25 °C		- 3.5		
Continuous Source-Drain Diode Current	T _A = 25 °C	- I _S	- 2.1 ^{a, b}		
	T _C = 25 °C		4.2		
Manifestore Device Distriction	T _C = 70 °C		2.7	10/	
Maximum Power Dissipation	T _A = 25 °C	P _D	2.5 ^{a, b}	W	
	T _A = 70 °C		1.6 ^{a, b}		
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	40	50	°C/W	
Maximum Junction-to-Foot	Steady State	R _{thJF}	24	30		

Notes

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under Steady State conditions is 95 °C/W.
- d. Based on $T_C = 25$ °C.



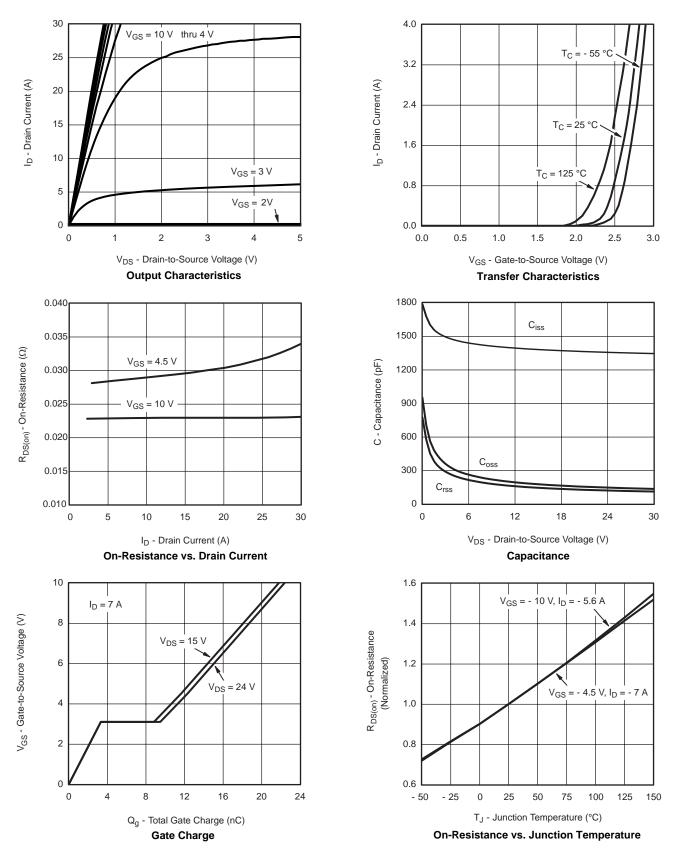
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V, } I_{D} = -250 \mu\text{A}$	- 30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	1 - 250 uA		- 31		m) //9/	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		4.5		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.0		- 2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zana Oata Valtana Busia Oamaat		V _{DS} = - 30 V, V _{GS} = 0 V			- 1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 55 °C			- 5	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -10 \text{ V}$	- 20			Α	
	D	V _{GS} = - 10 V, I _D = - 7.0 A	0.018				
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 5.6 A		0.024		Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 7.0 A		18		S	
Dynamic ^b				l			
Input Capacitance	C _{iss}			1455			
Output Capacitance	C _{oss}	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		180		pF	
Reverse Transfer Capacitance	C _{rss}			145			
T		$V_{DS} = -15 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -7.0 \text{ A}$		25	38		
Total Gate Charge				13	20	nC	
Gate-Source Charge	Q _{qs}	$V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -7.0 \text{ A}$		3.5			
Gate-Drain Charge	Q_{gd}			5.5			
Gate Resistance	R_g	f = 1 MHz	0.4	2.0	4.0	Ω	
Turn-On Delay Time	t _{d(on)}			10	20		
Rise Time				13	20	1	
Turn-Off DelayTime	t _{d(off)}	$I_{D} \cong -5.6 \text{ A}, V_{GEN} = -10 \text{ V}, R_{q} = 1 \Omega$		23	35	1	
Fall Time	t _f			9	18	1	
Turn-On Delay Time	t _{d(on)}			38	57	ns	
Rise Time	t _r	$V_{DD} = -15 \text{ V}, R_{L} = 2.7 \Omega$		89	134		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -5.6 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_q = 1 \Omega$		22	33		
Fall Time	t _f	· ·		11	17		
Drain-Source Body Diode Characteris	tics			l			
Continous Source-Drain Diode Current	I _S	T _C = 25 °C			- 6.5		
Pulse Diode Forward Current	I _{SM}	Ü			- 30	A	
Body Diode Voltage	V _{SD}	I _S = - 5.6 A, V _{GS} = 0 V		- 0.71	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			22	33	ns	
Body Diode Reverse Recovery Charge	ary Charge O			17	26	nC	
Reverse Recovery Fall Time	t _a	$I_F = -5.6 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 °C$		13		1	
Reverse Recovery Rise Time	t _b			9		ns	

Notes:

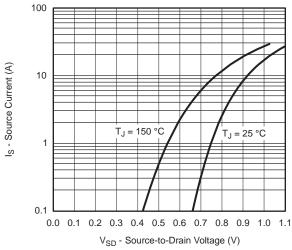
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

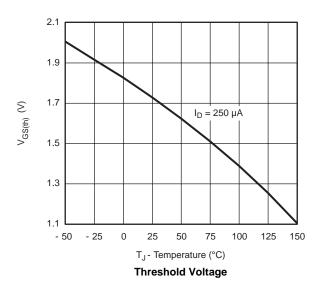








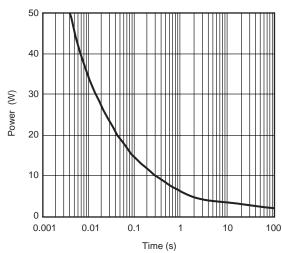
Source-Drain Diode Forward Voltage



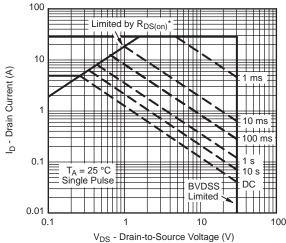
C 0.04 C 0.04 C 0.02 C 0.00 C

V_{GS} - Gate-to-Source Voltage (V)

On-Resistance vs. Gate-to-Source Voltage



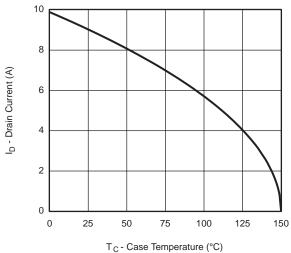
Single Pulse Power, Junction-to-Ambient



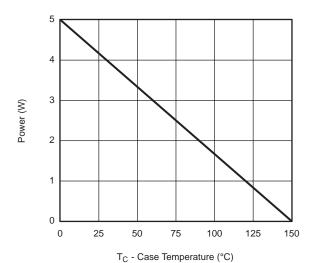
* V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

Safe Operating Area

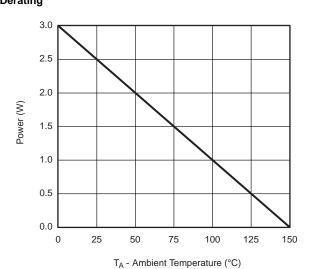




Current Derating*



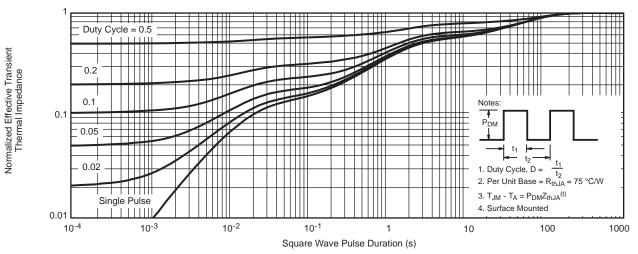
Power, Junction-to-Foot



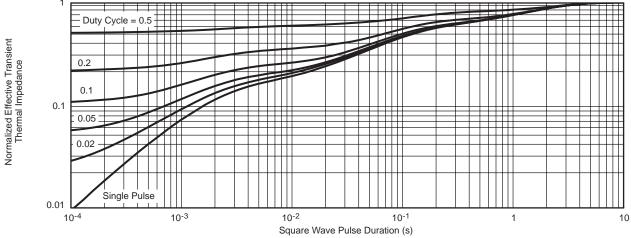
Power Derating, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit





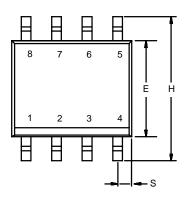
Normalized Thermal Transient Impedance, Junction-to-Ambient



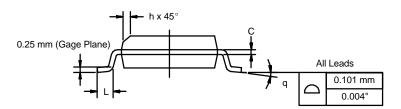
Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







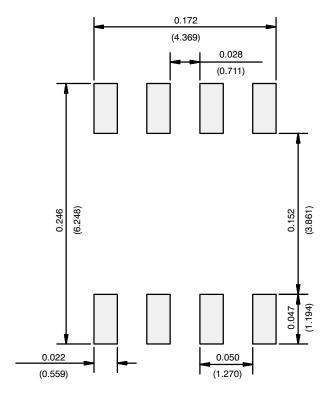
	MILLIMETERS		LLIMETERS INC			
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
Е	3.80	4.00	0.150	0.157		
е	1.27 BSC		0.050 BSC			
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
FCN: C-06527-Rev I 11-Sep-06						

ECN: C-06527-Rev. I, 11-Sep-06

DWG: 5498



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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